

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20180920001.0 Datasheet for SN54LVCH245A, SN74LVCH245A Information Only

Date:September 20, 2018To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN ww admin team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

SN74LVCH245ANSR SN74LVCH245APWR SN74LVCH245ADGVR SN74LVCH245APW

CUSTOMER PART NUMBER null

null null null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180920001.0	PCN Date: Se	tember 20, 2	018	
Title: Datasheet for	or SN54LVCH245A, SN74L		•		
Customer Contact: PCN Manager			ept: Qua	ality Services	
Change Type:					
Assembly Site	Design		Wafer Bum		
	Assembly Process Data Sheet			Wafer Bump Material	
Assembly Materia		iber change		Wafer Bump Process Wafer Fab Site	
Mechanical Specification Test Site Packing/Shipping/Labeling Test Process				Wafer Fab Materials	
<u> </u>			Wafer Fab		
	Notificat	on Details			
Description of Change					
The product datasheet The following change l	orporated is announcing a (s) is being updated as su nistory provides further de	mmarized below.	notification.		
TEXAS INSTRUMENTS SCES008Q – JULY 1995–REVISED SEPTER					
Changes from Revision P (July 2014) to Revision Q			Page	
Changed part number co	lumn to include specific orderable	parts			
	GQN.				
Added ZXY package pind	out section			6	
	gs to ESD ratings				
	ture from ESD Ratings table				
	mmercial device specifications in ary device specifications.				
	atures.				
	ut Types, Clamp Diode Structure,				
The datasheet number	will be changing				
Device Family		Change From	: Char	nge To:	
		SCES00		SCES008Q	
SCES008P SCES008 These changes may be reviewed at the datasheet links provided.					
http://www.ti.com/pro					
Reason for Change:					
To accurately reflect d					
	on Fit, Form, Function,				
No anticipated impact. the actual device.	This is a specification cha	nge announcement	only. There a	re no changes to	
	identification resulting	from this PCN:			
None.	a shanca don resulting				
Product Affected:					
5962-9754301Q2A	SN74LVCH245ADBRE4	SN74LVCH245APW	SN741	VCH245ARGYRG4	
5962-9754301QRA	SN74LVCH245ADGVR	SN74LVCH245APW		VCH245AZQNR	
5962-9754301QKA	SN74LVCH245ADGVR	SN74LVCH245APW		VCH245AZXYR	
5962-9754301QSA	SN74LVCH245ADGVRE4	SN74LVCH245APW		LVCH245AFK	
5962-9754301VRA	SN74LVCH245ADWR	SN74LVCH245APW		LVCH245AJ	
	SN74LVCH245ADWRG4	SN74LVCH245APW	I SNJ54	LVCH245AW	
5962-9754301VSA SN74LVCH245ADBR	SN74LVCH245ANSR	SN74LVCH245ARG			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail	
USA	PCNAmericasContact@list.ti.com	
Europe	PCNEuropeContact@list.ti.com	
Asia Pacific	PCNAsiaContact@list.ti.com	
Japan	PCNJapanContact@list.ti.com	